

A 110nm CMOS process for fully-depleted pixel sensors

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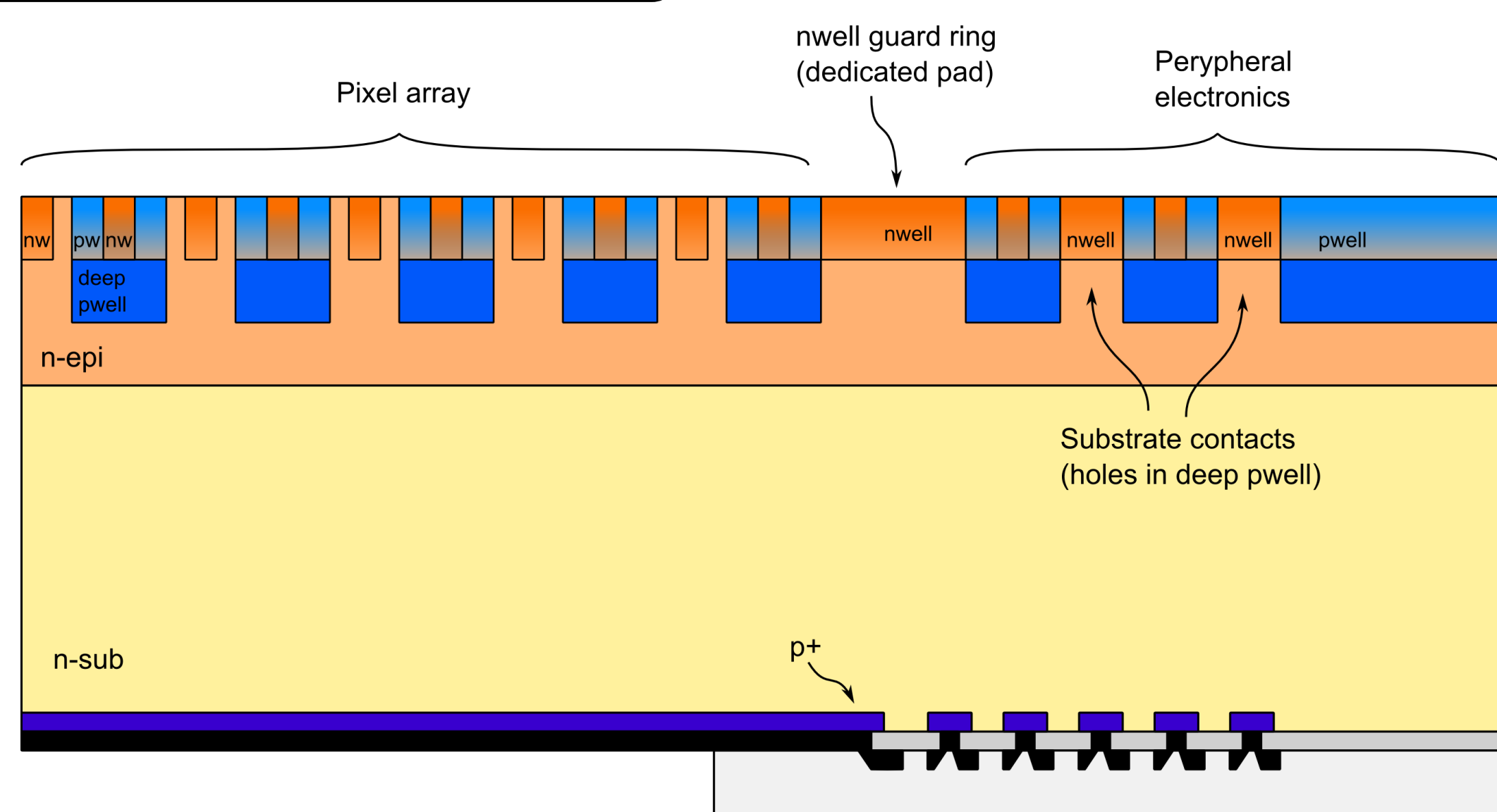
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Concept

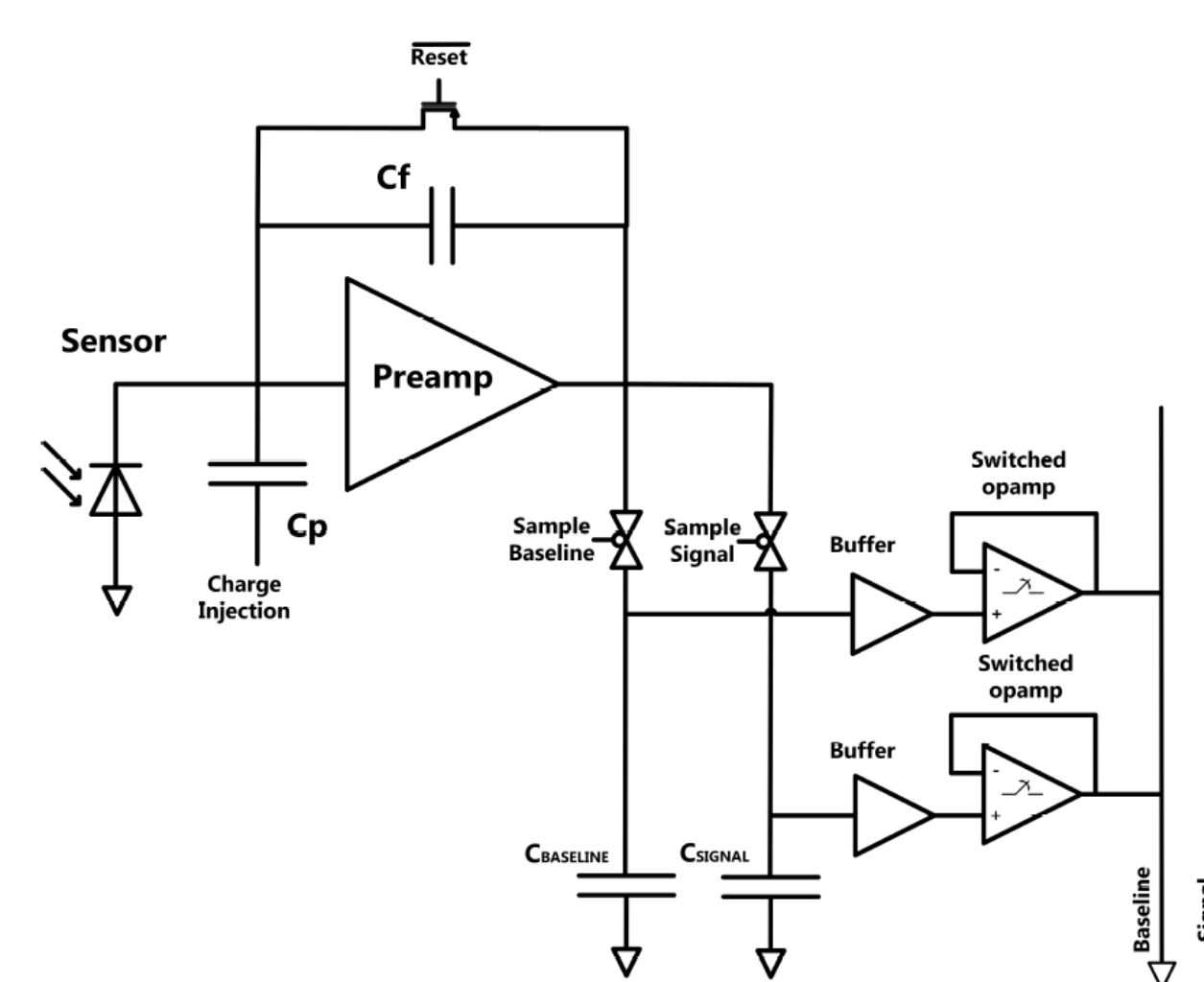


- Modified 110nm CMOS process
- 1.2V thin-oxide transistors for high radiation resistance
- Fully-depleted n-type High Resistivity substrate with 300 μ m thickness
- Backside processing: p+ implantation, metal and passivation
- Depletion region extending from the backside

Implementation

Chip 1: pixel array MATISSE:

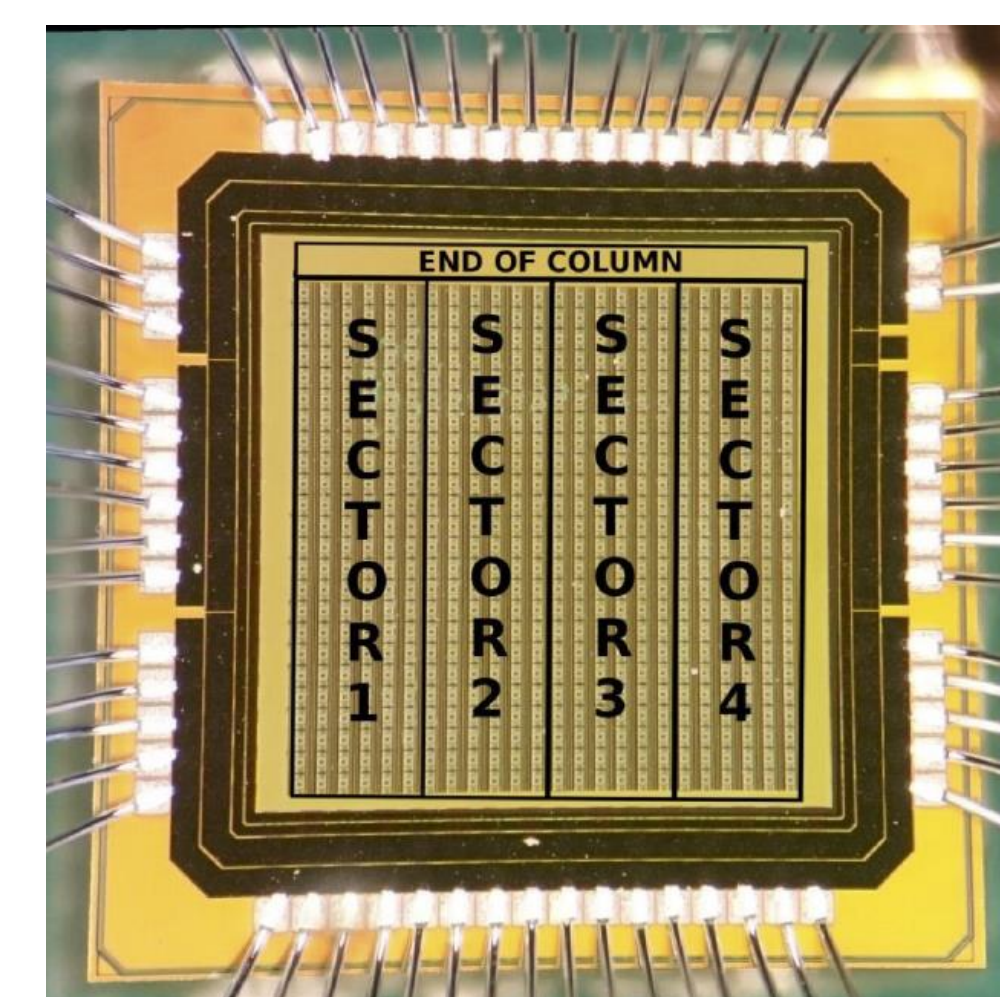
- 24 x 24 pixel array
- Pixel size: 50 μ m x 50 μ m
- In-pixel charge integrating amplifier
- In-pixel Sample-and-Hold and buffer amplifiers



MATISSE pixel schematic diagram

Chip 2: test structures:

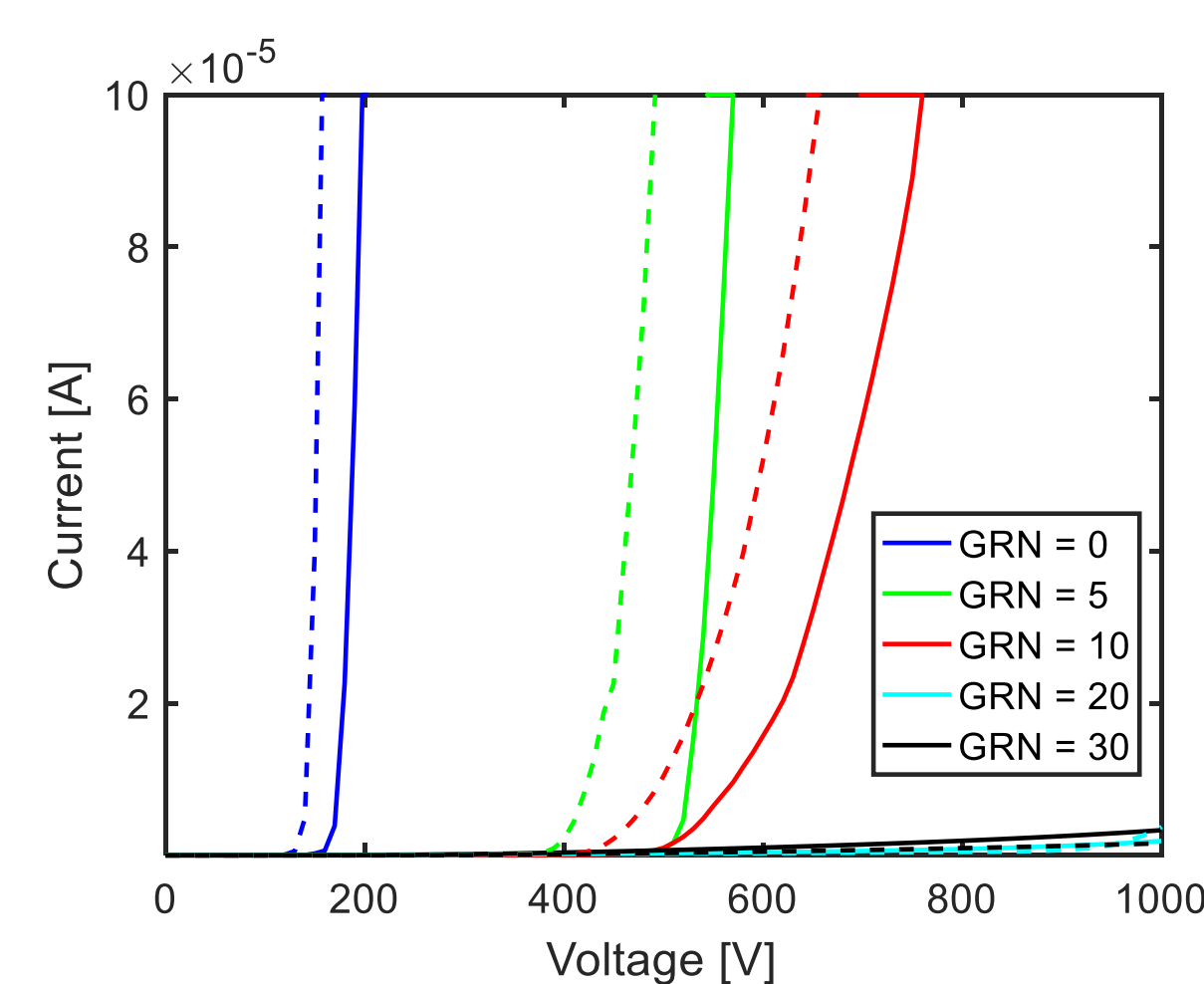
- Backside diodes** with different terminations
- Pseudo-pixel structures:** arrays of collection diodes with the same geometry and doping of MATISSE pixels, but without electronics



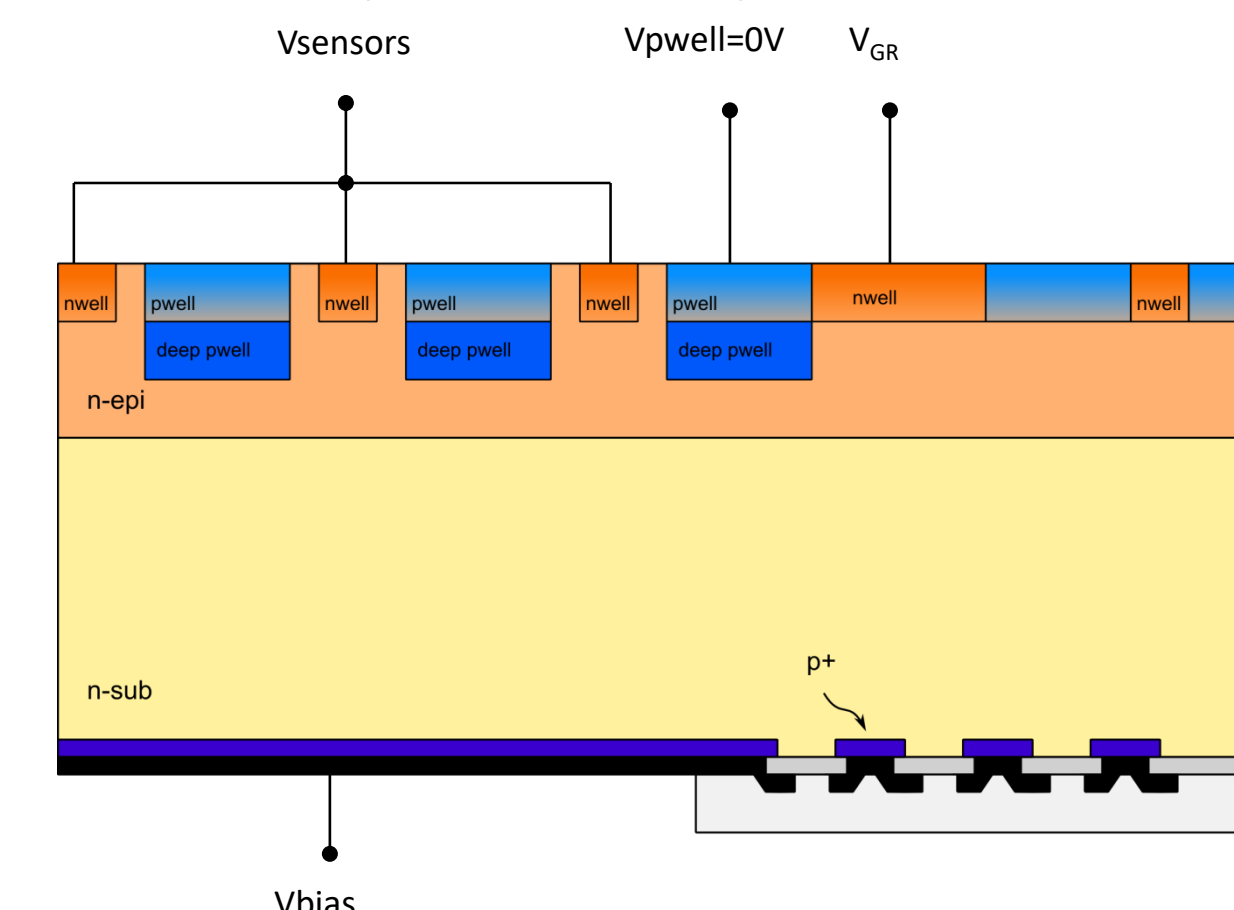
MATISSE chip micrograph

Characterization – Test structures

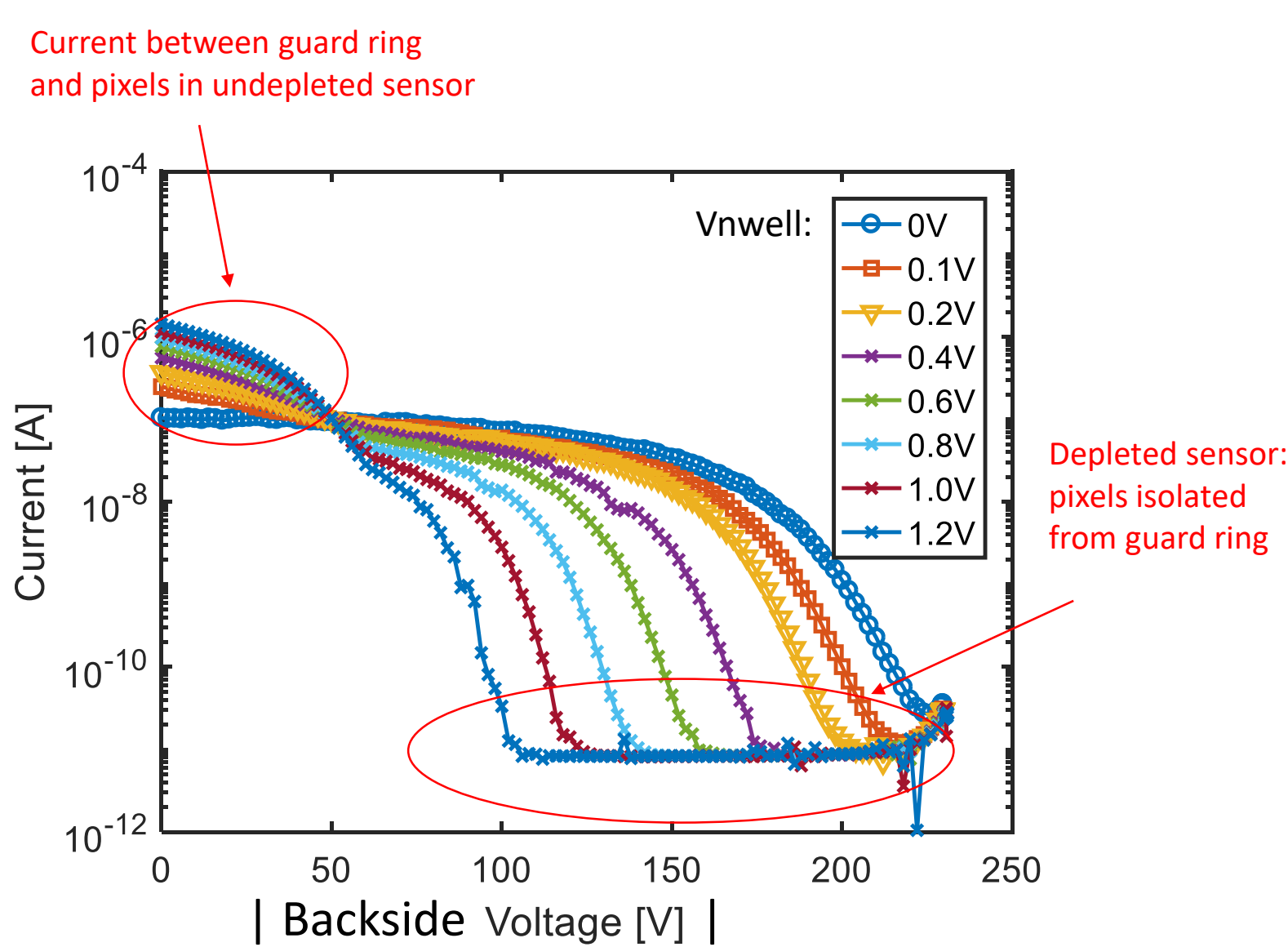
Current-Voltage curves of backside diodes with different Guard Ring Number (GRN)
Continuous lines: unirradiated diodes
Dashed lines: irradiated diodes (1Mrad)



Pseudo-pixels: 8x8 array of 50 μ m x 50 μ m pixels with 20 μ m x 20 μ m sensor size. All the sensor nodes are connected together.
• DC measurements: readout with SMU
• Dynamic characterization: fast transimpedance amplifier

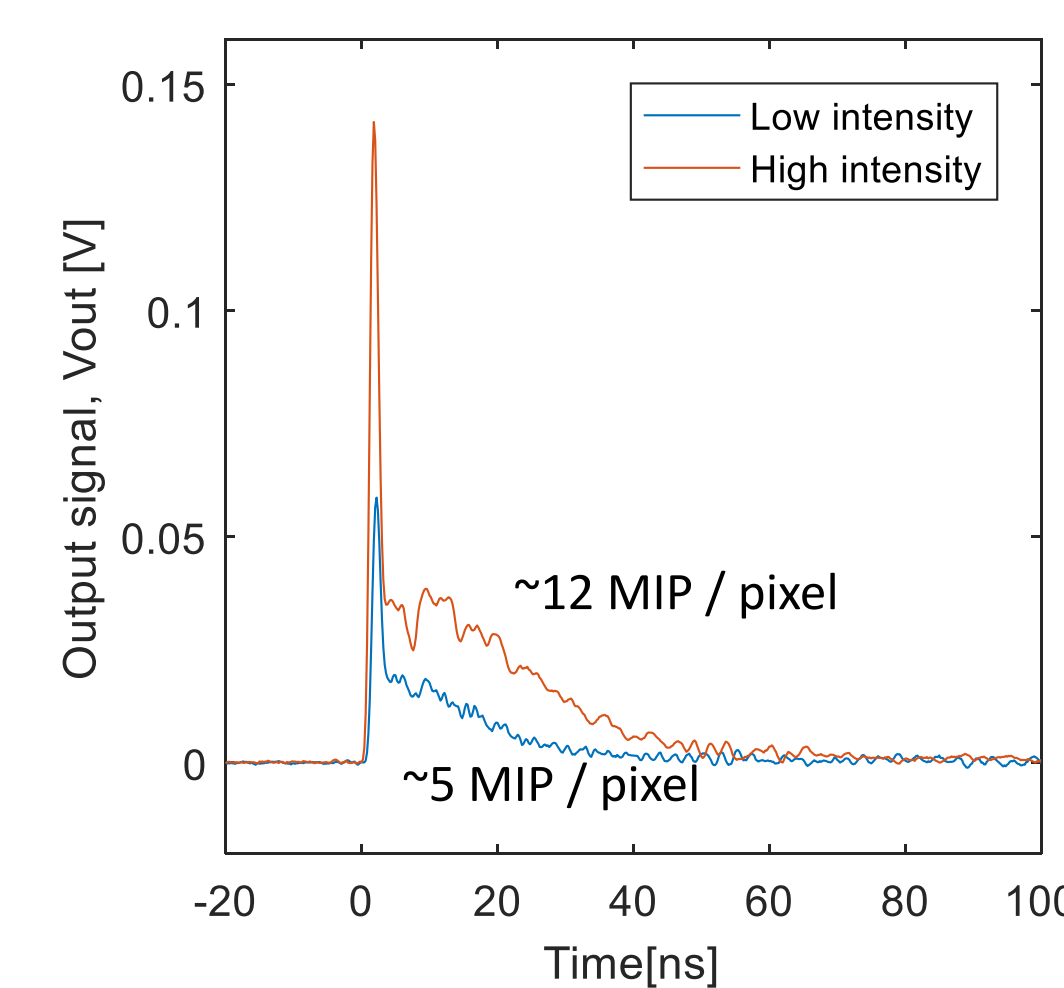


Dark current flowing in pseudo-pixels: backside depletion voltage depends on the voltage applied to the sensors at the frontside



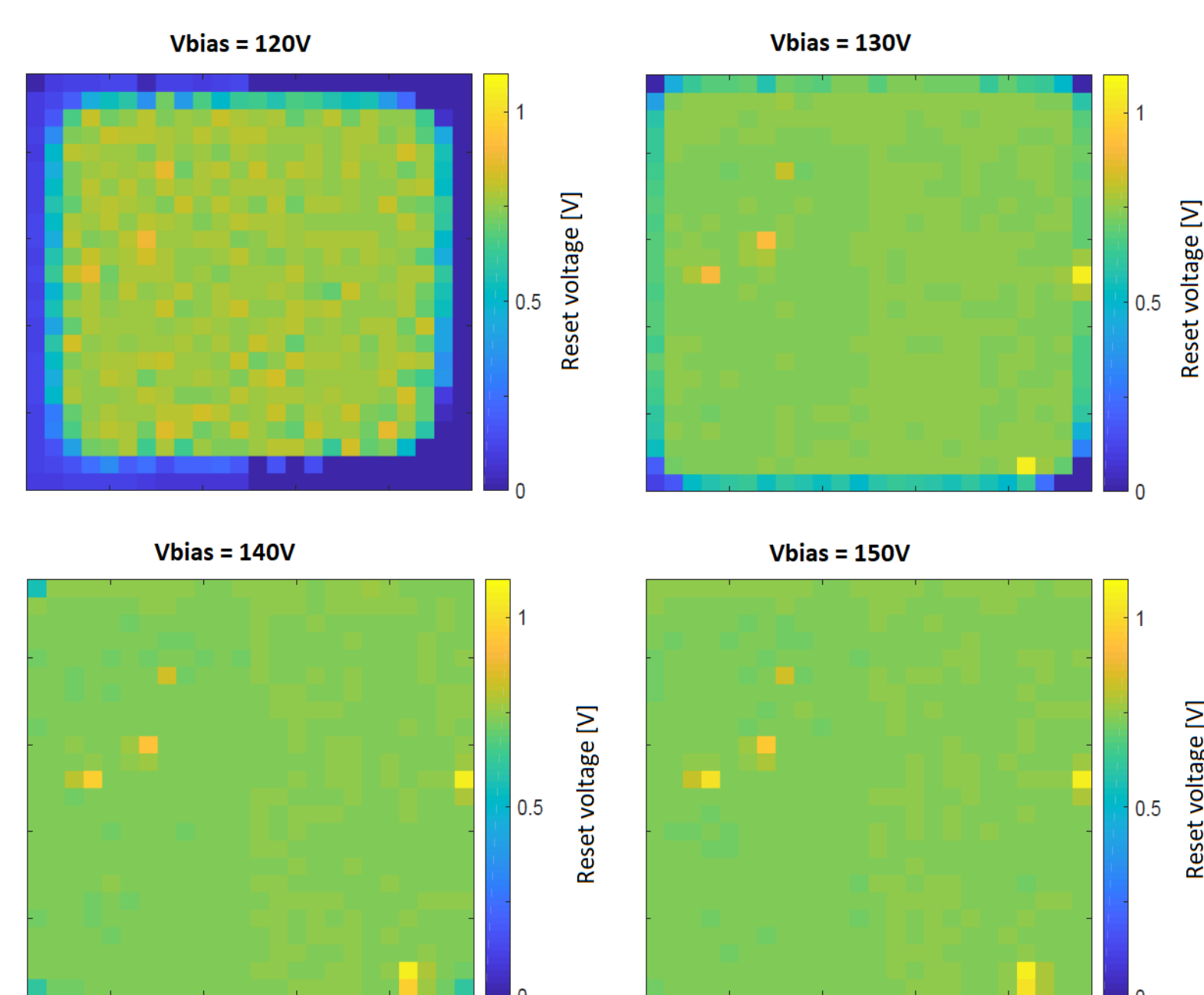
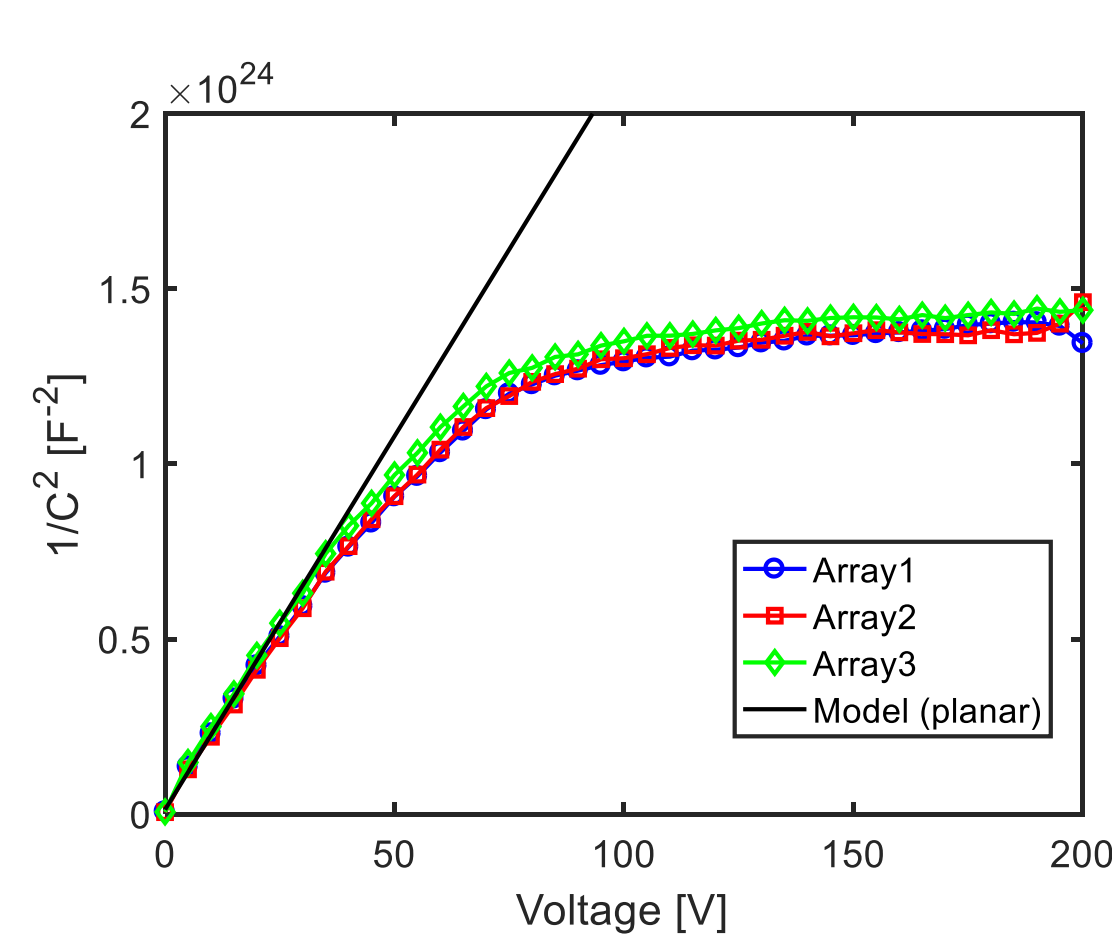
Signal collection:

- Sensor node current read out with wideband (1GHz) amplifier
- Flood illumination (unfocused laser)
- Wavelength: 1060 nm.



Characterization – Pixel array

Capacitance-Voltage curves of the array backside diodes: capacitance is constant above 140 – 150V

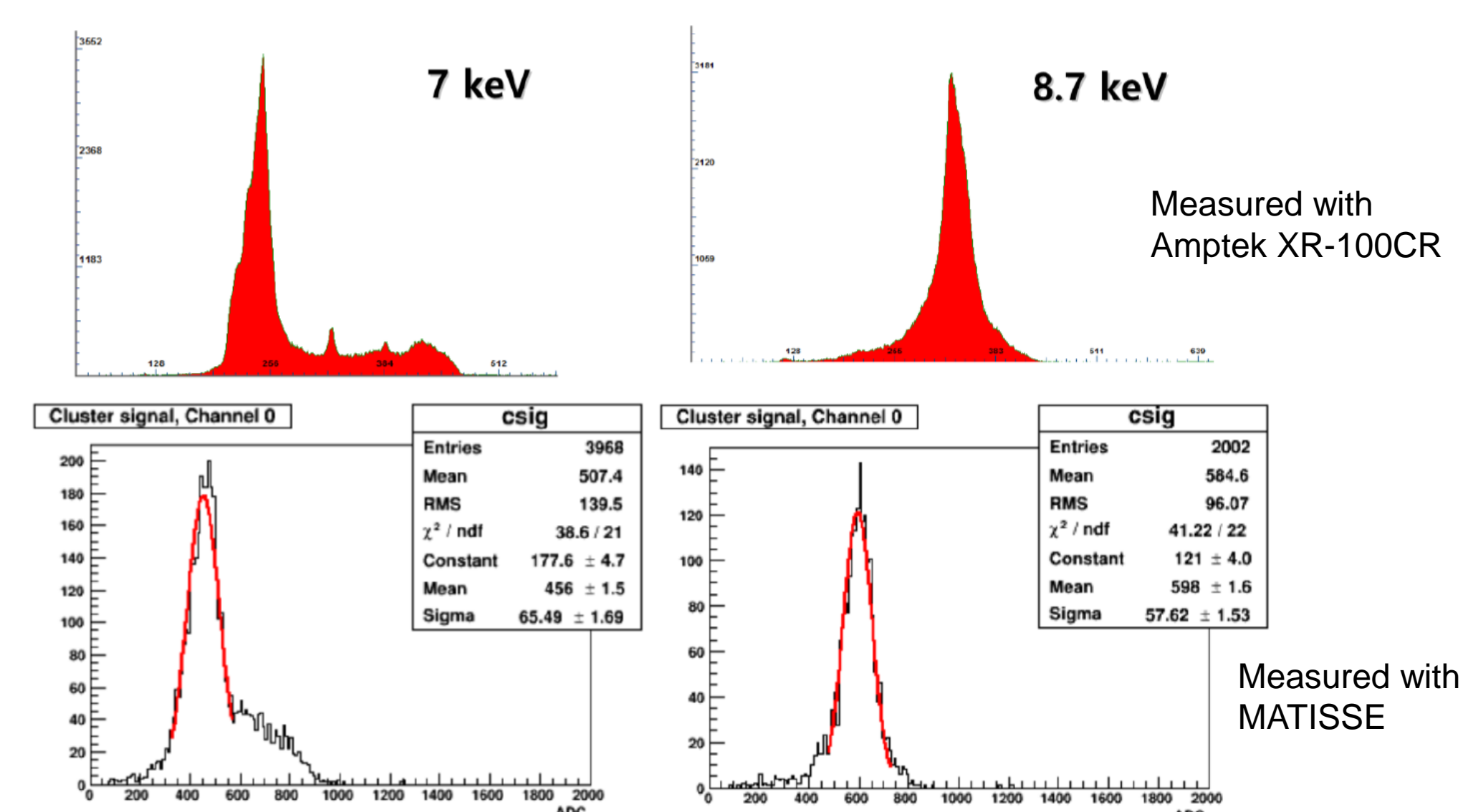


Map of the pixel reset voltage:

120 – 130V: high leakage at the border of the array: incomplete depletion

140 – 150V: low leakage: complete depletion

Measurement of monochromatic X-ray spectra



Work in progress

- New run with **different thickness:**
100 μ m for particle tracking
400 μ m for photon science
- Full characterization of radiation damage effects with ionizing and non-ionizing radiation
- Design of a large-area pixel sensor for efficiency studies

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